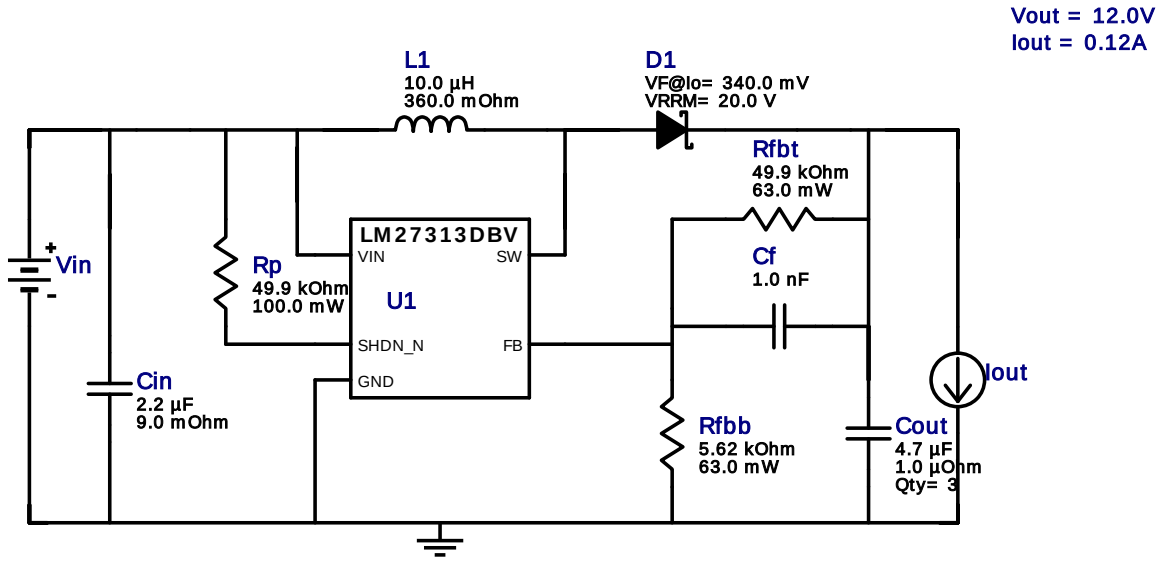
VinMin = 5.6V
VinMax = 6.0V
Vout = 12.0V
Iout = 0.12A

Device = LM27313XMF/NOPB
Topology = Boost
Created = 2023-06-06 03:47:34.140
BOM Cost = NA
BOM Count = 11
Total Pd = 0.24W

WEBENCH® Design Report

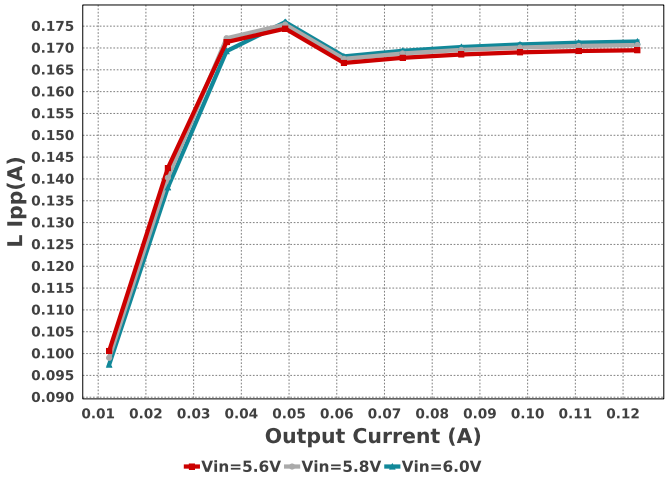
Design : 29 LM27313XMF/NOPB
LM27313XMF/NOPB 4.5V-5.5V to 12.00V @ 0.123A



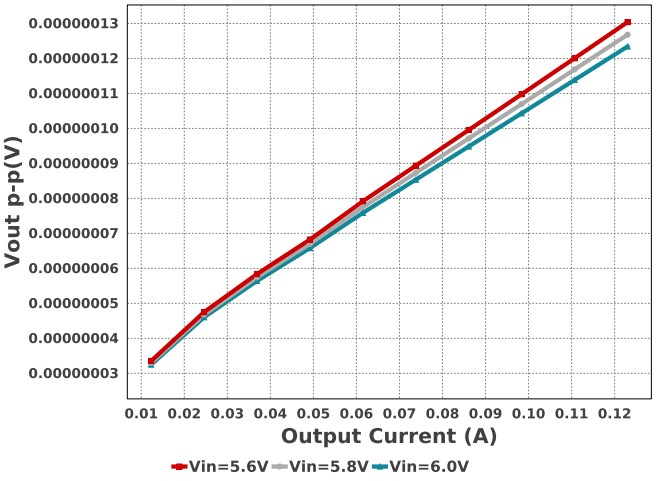
Electrical BOM

Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Cf	CUSTOM	CUSTOM Series= C0G/NP0	Cap= 1.0 nF VDC= 50.0 V IRMS= 0.0 A	1	NA	0805 0 mm²
Cin	MuRata	GRM188R71A225KE15D Series= X7R	Cap= 2.2 uF ESR= 9.0 mOhm VDC= 10.0 V IRMS= 3.3 A	1	$0.02	0603 5 mm²
Cout	CUSTOM	CUSTOM Series= X5R	Cap= 4.7 uF ESR= 1.0 uOhm VDC= 25.0 V IRMS= 2.8 A	3	NA	0805 0 mm²
D1	Fairchild Semiconductor	MBR1020VL	VF@Io= 340.0 mV VRRM= 20.0 V	1	$0.06	SOD-123F 12 mm²
L1	Taiyo Yuden	CBC2518T100M	L= 10.0 µH 360.0 mOhm	1	$0.09	CBC2518 10 mm²
Rfbb	CUSTOM	CUSTOM Series= CRCW..e3	Res= 5.62 kOhm Power= 63.0 mW Tolerance= 1.0%	1	NA	0402 0 mm²
Rfbt	CUSTOM	CUSTOM Series= CRCW..e3	Res= 49.9 kOhm Power= 63.0 mW Tolerance= 1.0%	1	NA	0402 0 mm²
Rp	CUSTOM	CUSTOM Series= ?	Res= 49.9 kOhm Power= 100.0 mW Tolerance= 1.0%	1	NA	0603 0 mm²
U1	Texas Instruments	LM27313XMF/NOPB	Switcher	1	$0.70	DBV0005A 15 mm²

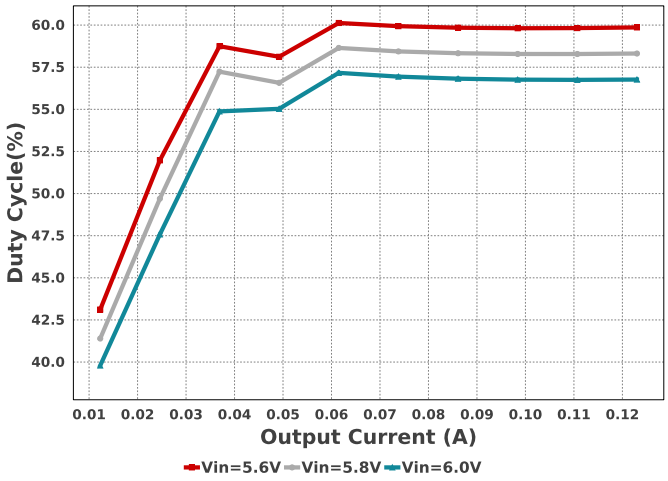
L Ipp



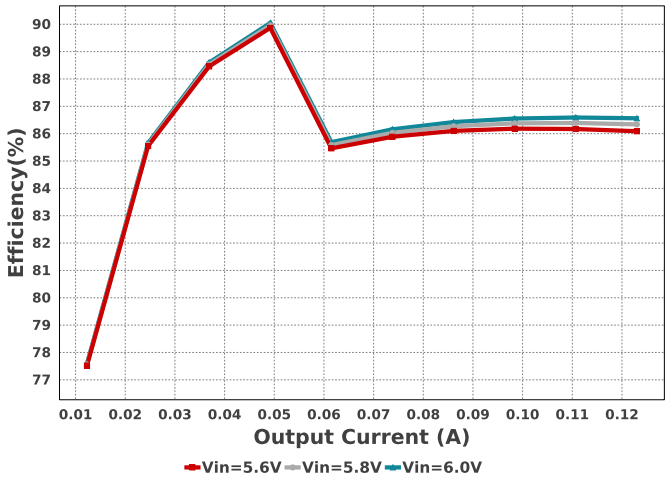
Vout p-p



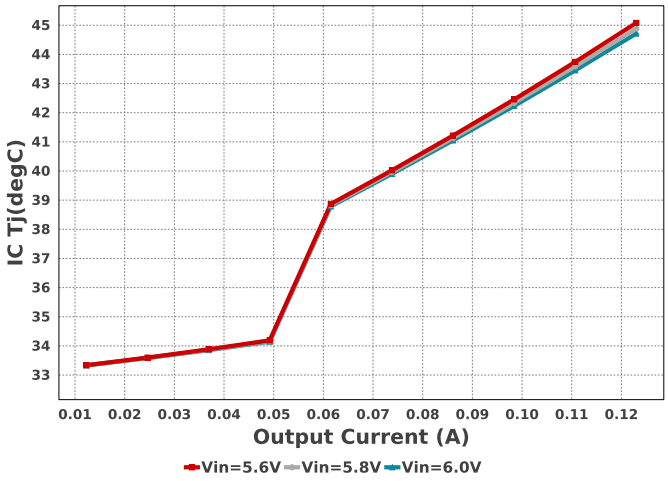
Duty Cycle



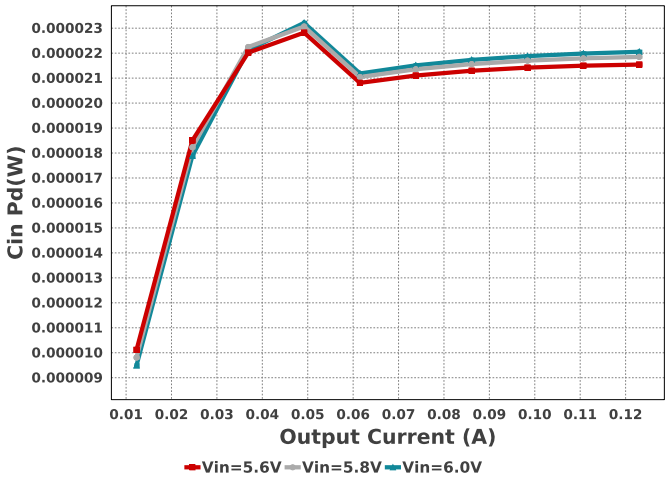
Efficiency

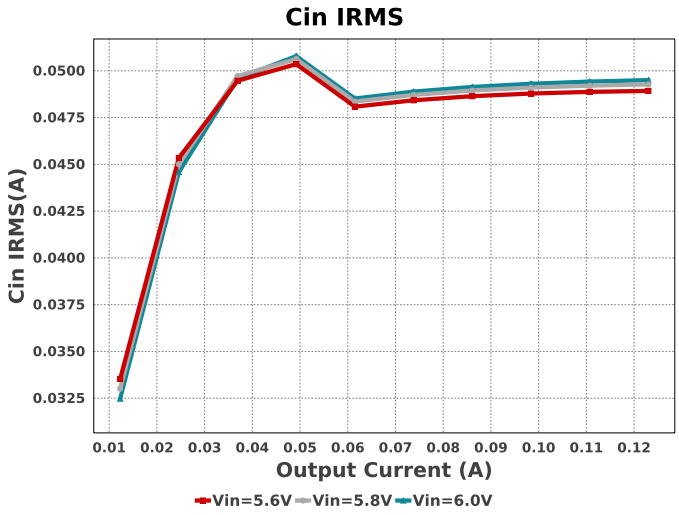


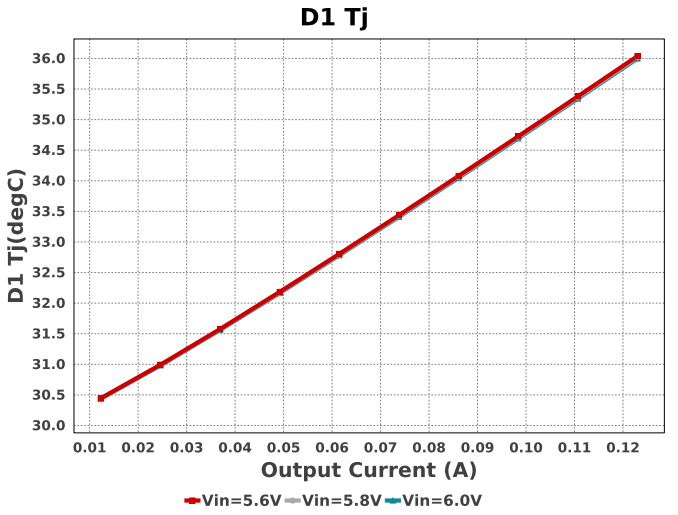
IC Tj

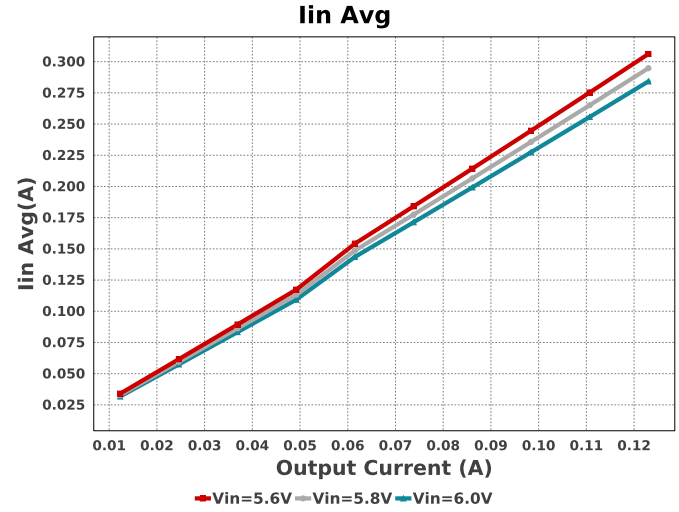


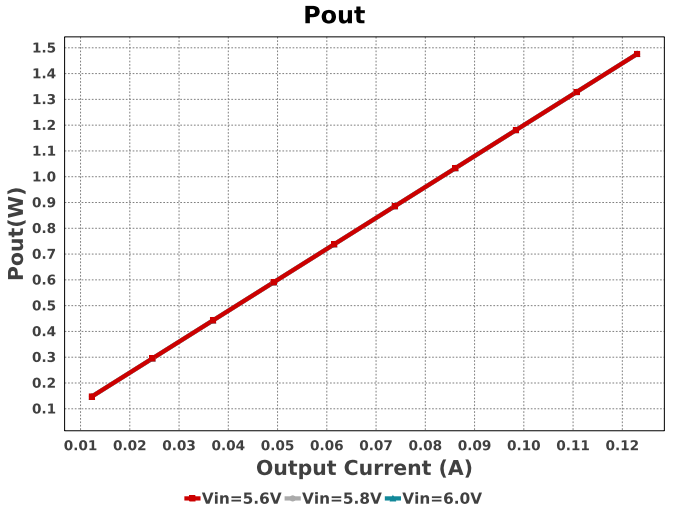
Cin Pd

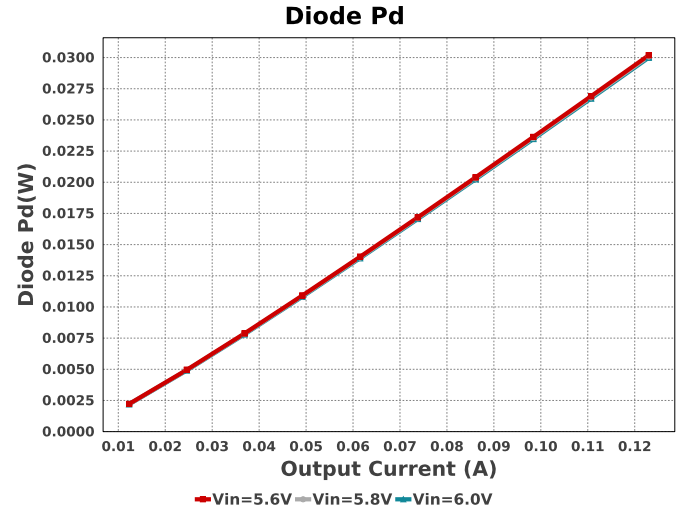


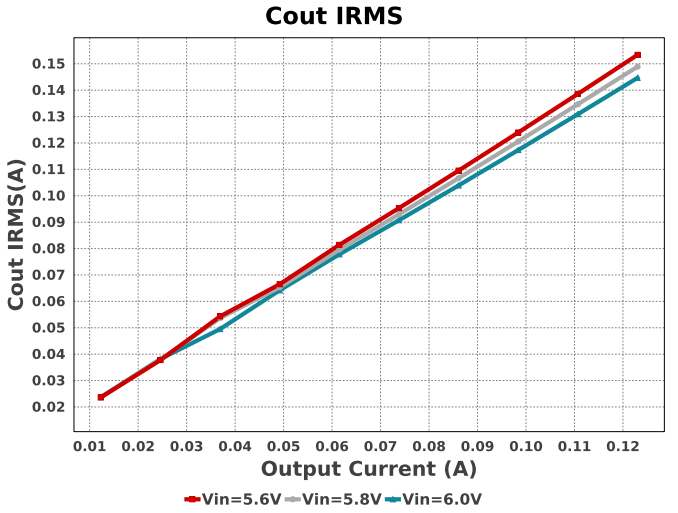


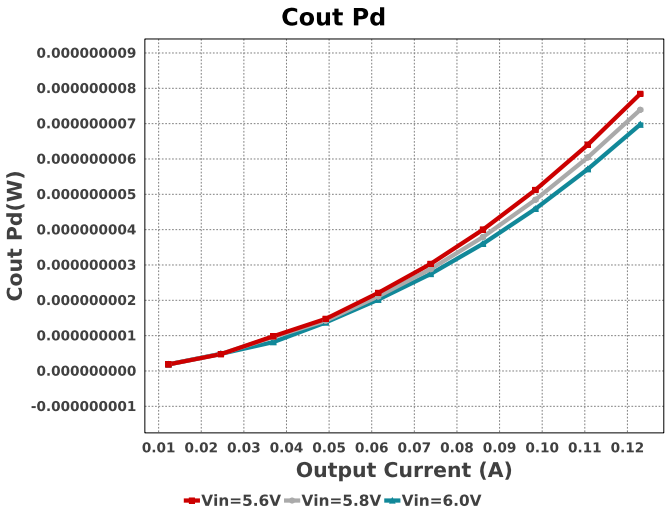


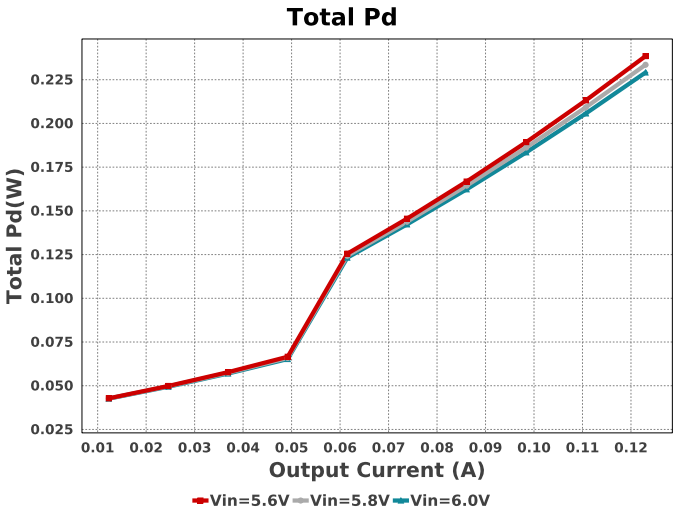


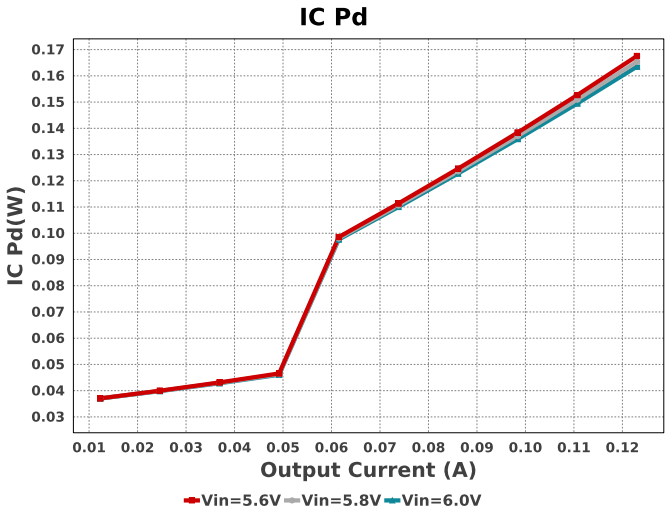


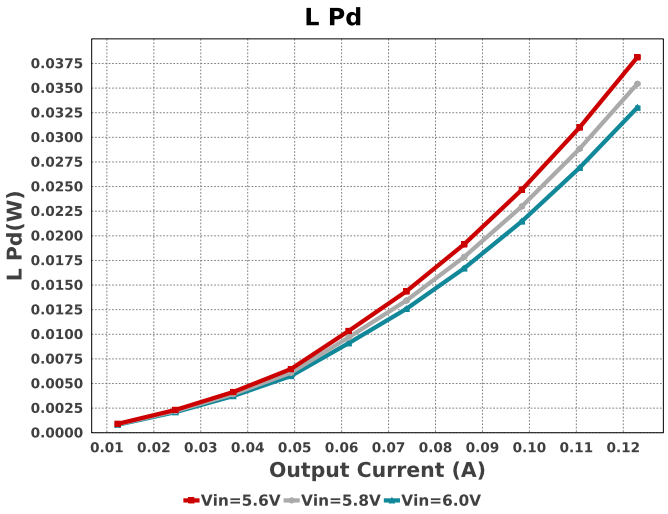












Operating Values

#	Name	Value	Category	Description
1.	BOM Count	11		Total Design BOM count
2.	Total BOM	NA		Total BOM Cost
3.	Cin IRMS	48.925 mA	Capacitor	Input capacitor RMS ripple current
4.	Cin Pd	21.543 µW	Capacitor	Input capacitor power dissipation
5.	Cout IRMS	153.374 mA	Capacitor	Output capacitor RMS ripple current
6.	Cout Pd	7.841 nW	Capacitor	Output capacitor power dissipation
7.	D1 Tj	36.038 degC	Diode	D1 junction temperature
8.	Diode Pd	30.19 mW	Diode	Diode power dissipation
9.	IC Pd	167.57 mW	IC	IC power dissipation
10.	IC Tj	45.081 degC	IC	IC junction temperature
11.	Iin Avg	306.16 mA	IC	Average input current
12.	L Ipp	169.48 mA	Inductor	Peak-to-peak inductor ripple current
13.	L Pd	38.134 mW	Inductor	Inductor power dissipation
14.	Cin Pd	21.543 µW	Power	Input capacitor power dissipation
15.	Cout Pd	7.841 nW	Power	Output capacitor power dissipation
16.	Diode Pd	30.19 mW	Power	Diode power dissipation
17.	IC Pd	167.57 mW	Power	IC power dissipation
18.	L Pd	38.134 mW	Power	Inductor power dissipation
19.	Total Pd	238.504 mW	Power	Total Power Dissipation
20.	Duty Cycle	59.861 %	System Information	Duty cycle
21.	Efficiency	86.089 %	System Information	Steady state efficiency
22.	FootPrint	79.0 mm^2	System Information	Total Foot Print Area of BOM components
23.	Frequency	1.6 MHz	System Information	Switching frequency
24.	Iout	123.0 mA	System Information	Iout operating point
25.	Mode	CCM	System Information	Conduction Mode

#	Name	Value	Category	Description
26.	Pout	1.476 W	System Information	Total output power
27.	Vin	5.6 V	System Information	Vin operating point
28.	Vout Actual	12.151 V	System Information	Vout Actual calculated based on selected voltage divider resistors
29.	Vout Tolerance	1.816 %	System Information	Vout Tolerance based on IC Tolerance (no load) and voltage divider resistors if applicable
30.	Vout p-p	130.392 nV	System Information	Peak-to-peak output ripple voltage

Design Inputs

Name	Value	Description
Iout	123.0 m	Maximum Output Current
VinMax	6.0	Maximum input voltage
VinMin	5.6	Minimum input voltage
Vout	12.0	Output Voltage
base_pn	LM27313	Base Product Number
source	DC	Input Source Type
Ta	30.0	Ambient temperature

WEBENCH® Assembly

Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of Cin and Cout, and the inductance and DC resistance of L1 before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

Soldering Component to Board

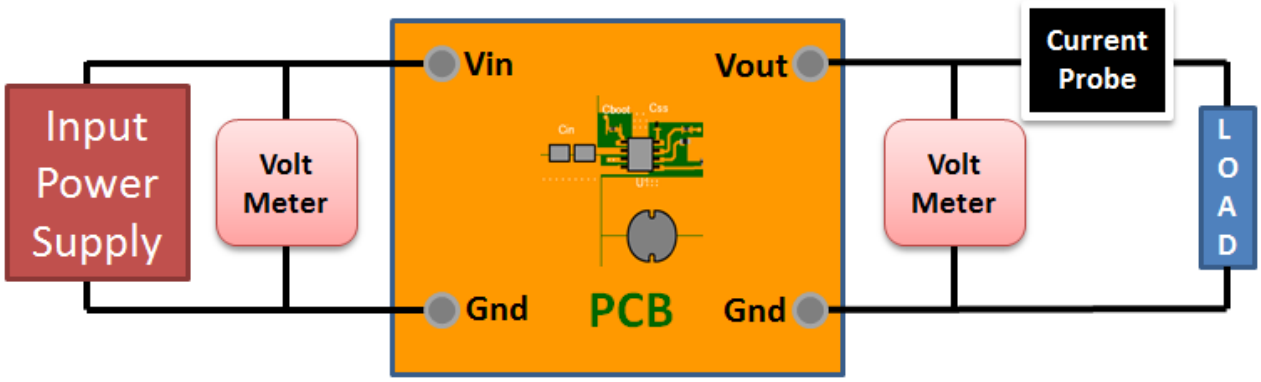
If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab town to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 5.6V and set the input supply's current limit to zero. With the input supply off connect up the input supply to Vin and GND. Connect a digital volt meter and a load if needed to set the minimum Iout of the design from Vout and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between Vin and GND, a load is connected between Vout and GND and a current meter is connected in series between Vout and the load. The load must be able to handle at least rated output power + 50% (7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.

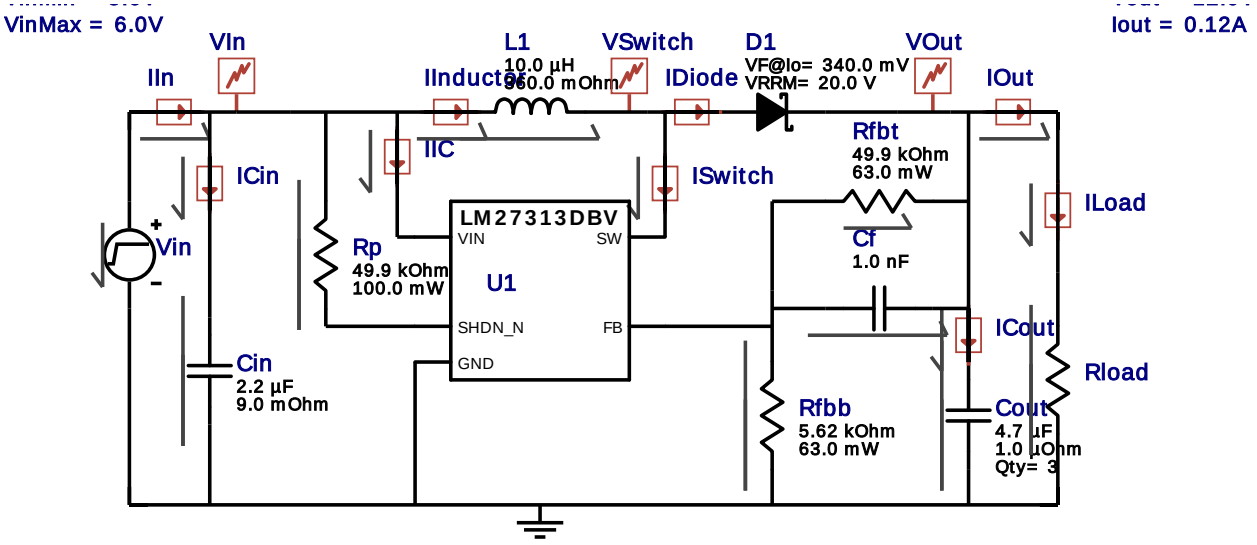


WEBENCH® Electrical Simulation Report

Design Id = 29

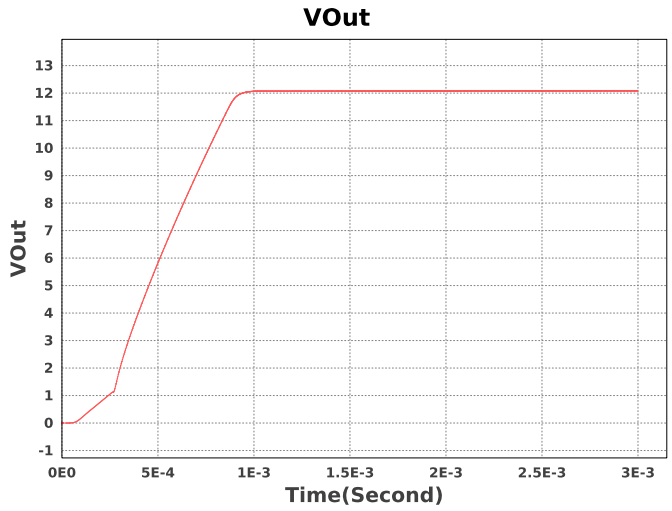
sim_id = 8

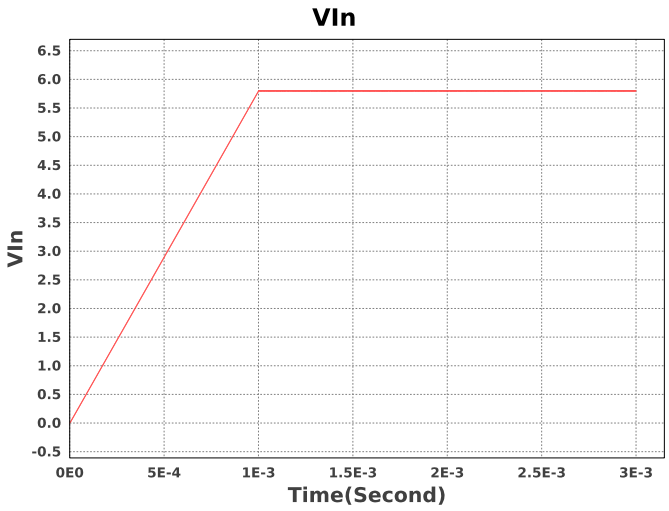
Simulation Type = Startup



Simulation Parameters

#	Name	Parameter Name	Description	Values
1.	Rload	R	Load Resistance	97.5609756097561 Ohm





Design Assistance

1. Master key : 61F4AB1D37815F31[v1]
2. **LM27313** Product Folder : http://www.ti.com/product/LM27313 : contains the data sheet and other resources.